

**AMENDMENTS TO THE ABSTRACT**

Please replace the paragraph at page 39 with the following rewritten paragraph:

-- ~~The invention provides a~~ dicing and die bonding pressure-sensitive adhesive sheet having a pressure-sensitive adhesive layer that exhibits excellent embedding properties in die bonding ~~and to~~ thereby ~~can~~ prevent formation of voids between die pads and the pressure-sensitive adhesive layer even when chips are mounted on ~~the~~ die pads ~~having~~ exhibiting great difference of differences in height. The dicing and die bonding pressure-sensitive adhesive sheet comprises a base material and a pressure-sensitive adhesive layer disposed thereon, the pressure-sensitive adhesive layer having a ratio ( $M_{100}/M_{70}$ ) of a modulus of elasticity at 100°C ( $M_{100}$ ) to a modulus of elasticity at 70°C ( $M_{70}$ ) being of 0.5 or less. --